



Customer Information Notification

202605002I : SC18IS606PW Datasheet Update

Note: This notice is NXP Company
Proprietary.

Issue Date: Jul 03, 2026 **Effective Date:** Jul 04, 2026

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Management summary

NXP announces a datasheet update for the SC18IS606PW.

Change Category

☐ Wafer	☐	☐ Test	☐
Fab	☐ Assembly	Process	☐ Design
Process	Process		
☐ Wafer	☐	☐ Test	☐
Fab	☐ Assembly	Equipment	☐ Errata
Materials	Materials		
☐ Wafer	☐	☐ Test	☐
Fab	☐ Assembly	Location	☐ Electrical
Location	Location	☐ Packing/Shipping/Labeling	spec./Test
			coverage
☐	☒ Other: Data Sheet		
☐ Firmware			

Notification Overview

Description

SC18IS606 Rev 1.1: <https://www.nxp.com/docs/en/data-sheet/SC18IS606.pdf>

The datasheet has been updated to correct/clarify a technical specification by removing an unsupported features:

Remove IDD(tpd) Total power-down mode supply current parameter from the Section 10 (Static Characteristics), Table 13.

It should be noted that there is no change in the device or performance.

Reason

The change was made to improve the accuracy and clarity of the datasheet, ensuring it reflects the actual behavior and supported features of the device. Incorrect information was removed to prevent confusion and potential misapplication by users and developers.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new data sheet will be issued

Additional information

Additional documents: [view online](#)

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name David Diaz

Position Product Marketer

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NXP Quality Management Team.

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12NC	Orderable Part Number	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	New 12NC	New Orderable Part Number	New Product Type	New Product Description	Product Line	Notes	5TG	Mask Set	Quality Segment
935420181118	SC18IS606PWJ	SC18IS606PW	I2C-bus to SPI bridge	(TJSSOP16	SOT403-1	RFS	No					BLT1				C (Non Automotive)